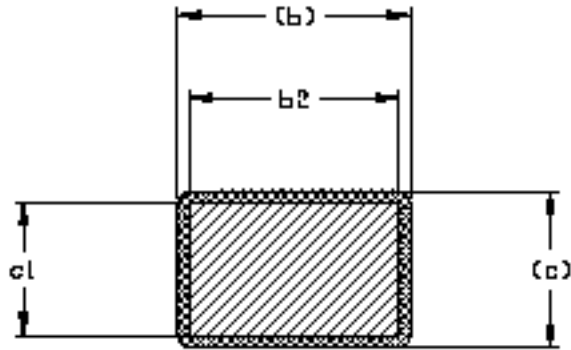
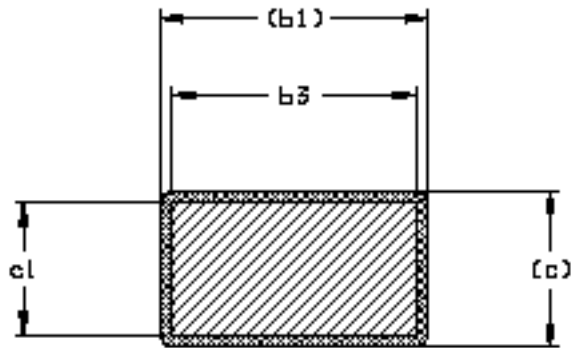
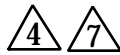


VIEW A - A

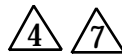
JEDEC SOLID STATE PRODUCT OUTLINES		THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY, CHANGES ARE LIKELY TO OCCUR.			
TITLE: Quad Flat Pack Surface Mount Thermally Enhanced Pkg		JESD-30 DESIGNATOR R-PQFP	ISSUE A	DATE: 05 - 98	TITLE: TO-271
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SECTION A-A



SECTION B-B



NOTES:

1. ALL DIMENSIONS IN MILLIMETER.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994.
3. DIMENSION "D1" & "E1" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSIONS b2, b3 AND c1 APPLY TO BASE METAL ONLY. DIMENSIONS b & c APPLY TO LEADS WITH FINISH.
5. APPLIES TO METAL SURFACE ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. SECTION A -A & B - B DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 TO 0.25 MILLIMETERS FROM THE LEAD TIP.
8. WRITE PROTECTED AREA, EXACT SIZE AND SHAPE OPTIONAL
9. DIMENSIONS "D2" AND "E2" TO BE DETERMINED AT DATUM PLANE H.
10. RESIN BLEED/FLASH INTRUSION ALLOWED AT TERMINAL BASE,(DEFINED BY SHADED AREA,) SHALL NOT EXCEED 0.45 MILLIMETERS. (per side)
11. RESIN BLEED/FLASH INTRUSION ALLOWED IN AREA DEFINED BY SHADED AREA, SHALL NOT EXCEED 0.25 MILLIMETERS. (per side)

SYMBOL	VARIATIONS						
	AA						
	MIN	NOM	MAX	NOTES			
A	1.45	1.55	1.65				
b	0.40	----	0.60	4,7			
b1	0.70	----	0.85	4,7			
b2	0.40	0.47	0.55	4,7			
b3	0.70	0.75	0.80	4,7			
b4	0.00	0.10	0.20				
b5	0.10	0.25	0.40				
c	0.35	----	0.45	4,7			
c1	0.35	0.38	0.42	4,7			
D	6.40	6.55	6.70				
D1	4.70	4.85	4.95	3			
D2		4.80 REF		9			
D3	3.30	3.45	3.60	11			
D4	1.65	1.75	1.90	10			
E	5.60	5.75	5.85				
E1	4.45	4.60	4.70	3			
E2		4.60 REF		9			
E3	1.80	1.85	1.95	11			
E4	0.40	0.50	0.60				
E5	0.40	0.50	0.60	10			
L	0.75	0.90	1.00				
L1	0.45	0.55	0.65				
L2	1.40	1.55	1.70				
L3	1.25	1.35	1.50				
L4	2.25	2.35	2.50				
NOTE	1, 2, 7						
REF.	11.10-370						
ISSUE	A						
JEDEC SOLID STATE PRODUCT OUTLINES		TITLE: R-PQFP Quad Flat Pack Surface Mount Thermally Enhanced Package		ISSUE A	DATE 05 - 98	TO -271	SHEET 3 OF 3